

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT7119913

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
APPLIED MATERIALS SINGAPORE TECHNOLOGY PTE. LTD.	01/07/2022
RECEIVING PARTY DATA	
Name:	Applied Materials, Inc.
Street Address:	3050 Bowers Avenue
City:	Santa Clara
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 5	
Property Type	Number
Application Number:	16944285
Application Number:	17486334
Application Number:	17486210
Application Number:	17483085
Application Number:	17508489
CORRESPONDENCE DATA	
Fax Number:	(732)935-7122
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	732-935-7100
Email:	lzaveta@mtiplaw.com
Correspondent Name:	MOSER TABOADA/ALAN TABOADA
Address Line 1:	1030 BROAD STREET
Address Line 2:	SUITE 203
Address Line 4:	SHREWSBURY, NEW JERSEY 07702
ATTORNEY DOCKET NUMBER:	AMST_TO_AMI_1-7-22
NAME OF SUBMITTER:	ALAN TABOADA
SIGNATURE:	/ALAN TABOADA/
DATE SIGNED:	01/13/2022
Total Attachments: 3	

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ASSIGNMENT

WHEREAS, Applied Materials Singapore Technology Pte. Ltd., a company organized under the laws of Singapore, and having a principal place of business at 8 Upper Changi Road North, Applied Materials Building, Singapore 506906 (hereinafter referred to as ASSIGNOR), is the owner of all right, title, and interest in, to, and under the patents and patent applications identified in the attached **Annex A**, and the inventions disclosed therein.

WHEREAS, Applied Materials, Inc., a corporation organized under the laws of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, CA 95054, U.S.A. (hereinafter referred to as ASSIGNEE), is desirous of acquiring the entire right, title, and interest in, to, and under the patents and patent applications identified in the attached **Annex A**, and the inventions disclosed therein.

NOW, THEREFORE, for good and valuable consideration acknowledged by said ASSIGNOR to have been received in full from said ASSIGNEE, ASSIGNOR, hereby sells, assigns, transfers, and conveys to ASSIGNEE or its successor and assigns, the entire right, title and interest in, to, and under the patents and patent applications identified in the attached **Annex A**, and the inventions disclosed therein, and any related patent applications, and all divisions, renewals, and continuations of any of the foregoing, and all patents which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for the patents, patent applications, and inventions in any country or countries other than the countries of the patents and patent applications in **Annex A** together with the right to file such applications and the right to claim for the same, the priority rights derived from the patents and patent applications, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed.


ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks of the United States, and any official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on patents and patent applications as aforesaid, to issue the same to the ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

ASSIGNOR hereby covenants and agrees that ASSIGNOR has full right to convey the entire interest assigned, and that ASSIGNOR has not executed, and will not execute, any agreement in conflict herewith.

ASSIGNOR hereby further covenants and agrees that ASSIGNOR will communicate to ASSIGNEE, its successor, legal representatives and assigns, any facts known to ASSIGNOR regarding the inventions, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue, and foreign applications, make all rightful oaths, and generally aid the ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for the inventions in all countries all at ASSIGNEE'S expense.

IN WITNESS WHEREOF, ASSIGNOR has executed and delivered this instrument to ASSIGNEE on the date indicated below.

January 7, 2022
Date


Signature(s)

Samuel K. Lee
Typed or printed name(s)

Director
Title(s) of person(s) signing

Applied Materials Singapore Technology Pte. Ltd.
Assignor name

ANNEX A

Serial Number	Docket Number	Filing Date	Title
16/944,285	44018114US01	07/31/2020	METHODS AND APPARATUS FOR BACKSIDE VIA REVEAL PROCESSING
17/486,334	44020151US1	09/27/2021	WATER VAPOR PLASMA TO ENHANCE SURFACE HYDROPHILICITY
17/486,210	44020186US1	09/27/2021	METHODS FOR SELECTIVE REMOVAL OF CONTACT OXIDES
17/483,085	44020187US1	09/23/2021	IN-SITU CALIBRATION/OPTIMIZATION OF EMISSIVITY SETTINGS IN VACUUM FOR TEMPERATURE MEASUREMENT
17/508,489	44020428US1	10/22/2021	METHODS AND APPARATUS FOR PROCESSING A SUBSTRATE